



Overview:

Keratherm Bond 100 RT is a 2 components structural bond adhesive, designed to provide structural bond for screwless applications in place of currently used semi-cured pads. Semi-cured may face temperature issues during shipping and have to ship by costly direct door to door freight.

Benefits:

- High bond strength
- Room temperature curing in 20 minutes
- Maximize surface conformability
- Thixotropic and filling surface structures

Applications:

- BGA
- CPU
- LED
- MosFet
- Heat sinks

Properties	Unit	Bond 100 RT	Test Method
Colour	-	Brown	Visual
Base Material	-	Silicone	-
Mixing Ratio	-	1 : 1	-
Curing (Room Temperature)	Minutes	20	Kerafol
Thermal Properties			
Thermal resistance R_{th}	K/W	0.83	Kerafol
Thermal conductivity λ	W/m-K	1.5	ASTM D 5470
Electrical Properties			
Dielectric breakdown $E_{d,ac}$	kV/mm	12	ASTM D 149
Mechanical Properties			
Measured thickness	mm	0.500	ASTM E 252
Hardness	Shore A	20 - 35	ASTM D 2240
Shear Strength	MPa	>15.0	Kerafol
Physical Properties			
Operating temperature	°C	-40 to +180	Kerafol
Density	g/cm ³	2.10	Kerafol
Viscosity (Shear rate 4 ⁻¹ /25°C)	Pas	20 - 40	Kerafol

* Data provided are nominal values that should not be used to write specifications. Users are advised to test and decide the suitability of the product to fit their applications.